

Completion Ceremony for New plant of Sumitomo Bakelite (Suzhou) Co., Ltd. for Epoxy Resin Molding compounds for Encapsulation of Semiconductor Devices

Tokyo, Japan – October 28, 2024, Sumitomo Bakelite Co., Ltd. (TOKYO: 4203 HQ: Shinagawa-ku, Tokyo, President and Representative Director: Kazuhiko Fujiwara) is pleased to announce that Sumitomo Bakelite (Suzhou) Co., Ltd. (Hereinafter, "SSB"), a group company in China, has completed the construction of a new plant for epoxy resin molding compounds for encapsulation of semiconductor devices, and that a completion ceremony was held on September 20th, 2024.

[SSB's New Plant of Epoxy Resin Molding Compounds for Encapsulation of Semiconductor Devices]

Sumitomo Bakelite Co., Ltd. holds the worldwide leading position in semiconductor encapsulation materials with a market share of approximately 40% (estimated by our company).

In order to meet customer needs, Sumitomo Bakelite Co., Ltd. has been expanding its production capacity in the growing China market, starting production in 1997 and expanding production lines at the current plant in July, 2021. The new plant was completed and a completion ceremony was held on September 20th inviting the Suzhou Industrial Park Management Committee, Suzhou local government officials, and those who contributed to the construction of the plant. The new plant is scheduled to begin full-scale mass production in 2025 as work progresses toward its official operation.



SSB's New Plant for Epoxy Resin Molding Compounds for Encapsulation of Semiconductor Devices

The new plant will ensure sufficient supply capacity by securing new land and building a plant in the Suzhou Industrial Park so as to expand SSB's total production capacity by 1.3 times. In addition to the traditional semiconductor-related applications such as smartphones, personal computers, and home appliances, the plant will increase its share in the China market for power devices, mobility applications, and advanced AI applications.

As a state-of-the-art production plant, the plant will employ process automation, automatic process monitoring system utilizing AI and IoT, and fully adopt electricity derived from renewable energy in compliance with China's increasingly stringent safety and environmental regulations. In addition, the plant will contribute to achieving carbon neutrality by installing the latest environmental protection equipment and producing products in a safe, secure, environmentally friendly, and energy-efficient manner.

Our group has four plants of Epoxy molding compounds for encapsulation of semiconductor devices in the Asian region, including China and Japan.

We aim to expand our business by developing a global strategy to ensure a stable supply of Epoxy resin molding compounds for Encapsulation of semiconductor devices to major markets and by responding accurately and promptly to customer needs in each region.

[Sumitomo Bakelite (Suzhou) Co., Ltd. New Plant Completion Ceremony]



Sumitomo Bakelite Co., Ltd. has decided to invest in this new plant to respond in a timely manner to the “Made in China 2025” initiative initiated by the Chinese government.

It will also be a strategic initiative to introduce our group's cutting-edge technology to create a smart factory.

Going forward, we will contribute to the further development of the semiconductor industry as a strategic base for our group.

Masayuki Inagaki, Executive Vice President, Sumitomo Bakelite Co., Ltd.

[Overview of SSB's New Plant]

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| Address | No. 102, Jiangpu Road, Suzhou Industrial Park, Suzhou, Jiangsu Province |
| Site area | Approx. 60,000m ² |
| Scheduled start of operations | Scheduled to start mass production in 2025 |
| Major production items | Epoxy resin molding compounds for encapsulation of semiconductor |
| Investment amount | Approx. 6.6 billion yen (Including land, buildings, production lines, ancillary facilities, etc.) |



View of a new plant

For further information:

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